

10/510,679 ~~MPA~~

AMENDMENTS TO THE SPECIFICATION:

In the title:

Please change the title to read as follows:

MANUFACTURING METHOD OF A SEMICONDUCTOR DEVICE  
UTILIZING A FLEXIBLE ADHESIVE TAPE.

Page 54:

Please substitute the following paragraph for the  
paragraph beginning at line <sup>19</sup>/<sub>26</sub>.

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The adhesive 50 used is an insulating adhesive which is  
~~stronger~~weaker in its adhesion to an adhesive (first  
adhesive) 26 for bonding a tape 1a and copper foil than in  
its adhesion to the silicon substrate of the semiconductor  
element 4. Therefore, when the tape 1a is peeled from the  
insulating resin layer 6, the adhesive 50 and the tape 1a  
(or the adhesive (first adhesive) 26) are peeled from each  
other in such a manner that the adhesive 50 remains on a  
back surface of the semiconductor element 4.

Page 55:

Please substitute the following paragraph for the  
paragraph beginning at line <sup>1</sup>/<sub>4</sub>.

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The adhesive 50 may be substituted by an adhesive tape  
both surfaces of which are adhesive surfaces. The adhesive